

METHOD OF MANUFACTURING WIRING BOARD

of 8/18/06
[0001] This is a divisional application of U.S. Application Serial No. 10/127,065 filed April 19, 2002, ^{now abandoned,} which claims priority to Japanese Patent Application No. 2001-124195 filed April 23, 2001, and the disclosure of which is incorporated herein by reference in its entirety.

Background of the InventionField of the Invention

[0002] The present invention relates to a method of manufacturing a wiring board including a manufacturing step of forming an insulating layer having a flat upper surface on a wiring layer having a wiring pattern, a composite sheet for manufacturing a wiring board to be used therein, and a wiring board which can be obtained by the manufacturing method. The present invention is prefer for a method of manufacturing a multilayer wiring board.

Description of the Related Art

[0003] In the steps of forming a core substrate, an insulating layer or the like of a printed wiring board to be used in electronic equipment or the like, conventionally, there has been used a prepreg in which a glass fiber fabric or a polymer nonwoven fabric is impregnated with a thermosetting resin and is half cured. The prepreg is thermally pressed together with copper foils provided on both surfaces, for example, so that a double-sided copper foils laminated plate can be obtained, and a wiring pattern is formed on the copper foil and can be thus used as the core substrate of a multilayer wiring board.

[0004] In recent years, the wiring board has a finer wiring pattern because of the high integration of a wiring, and furthermore, a multilayer structure is achieved and each layer is thinned. For this reason, in the case in which a glass fiber fabric impregnated with an epoxy resin is used for the prepreg, there is a problem in that drilling is carried out with difficulty due to a glass fiber when laser via processing is to be carried out. Therefore, there have been proposed various prepregs using, for a reinforcing phase, a polymer nonwoven fabric on which the laser via processing can be carried out more easily.

[0005] When an insulating layer is formed on a wiring layer having a wiring pattern by using the prepreg having the polymer nonwoven fabric for the reinforcing phase,